222 Install label in silkscreen box after final wash. Text shall be 8 pt. font. Text shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive. ESD precautions shall be observed.

222 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

222 These assemblies must comply with workmanship standards IPC-H-810 Class 2, unless otherwise specified.
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